COUNT	DESCRIPTION OF REVISI			ONS	BY	CHKD	D DATE COUNT			DESCRIPTION OF REVISIONS BY CHKD			DATE		
								\triangle							
abla								\triangle							
APPLICA	BLE ST	AND	ARD												
DATING	TEMPE	OPERATING TEMPERATURE RANGE			°C T	O +85	5 °C(NO	TE1	STOR TEM	AGE -10°C TO +60°C(No					E2)
RATING VOL		ΓAGI								RRENT 3 A					
						SF	ECIFI	<u>CA</u>	TIOI					- -	
ITEM			TEST METHOD REQUIREMENTS										QT	AT	
CONSTR														т	
GENERAL EXAMINATION		VISUALLY AND BY MEASURING INSTRUMENT. ACCORDING TO DRAWING.										×	×		
MARKING		CONFIRMED VISUALLY.										×	×		
1			TERISTICS												
CONTACT RESISTANCE		ICE	100 mA (DC OR 1000 Hz).							30 mΩ MAX.				×	
INSULATION RESISTANCE			500 V DC.							1000MΩ MIN.				×	_
VOLTAGE PROOF			650V AC FOR 1 min.							NO FLASHOVER OR BREAKDOWN.				×	
MECHAN	VICAL C	HAF	RACTE	RIST	rics										
MECHANICAL OPERATION			30 TIMES INSERTIONS AND EXTRACTIONS.							① CONTACT RESISTANCE: 30 mΩ MAX. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.				×	_
VIBRATION			FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.							① NO ELECTRICAL DISCONTINUITY OF 1μs.				×	_
SHOCK			490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.											×	
ENVIRO	NMENT	AI (I	
RAPID CHA			TEMPERATURE -55→ 5~35 →+85→ 5~35 °C							① CONTACT RE	ESISTANCE:	30 mg	2 MAX.		
TEMPERATURE			TIME 30→10~15→ 30 →10~15 min							② INSULATION MIN.	RESISTANC	E: 100	00 ΜΩ	×	
		UNDER 5 CYCLES.							③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.						
DAMP HEAT (STEADY STATE)			EXPOSED AT 40 ± 2 °C, 90 ∼ 95 %, 96 h.							 CONTACT RESISTANCE: 30 mΩ MAX. INSULATION RESISTANCE: 1000 MΩ MIN. NO DAMAGE, CRACK OR LOOSENESS 				×	
										OF PARTS.					ļ .—
RESISTANCE TO SOLDERING HEAT			SOLDER TEMPERATURE, 250±5°C, FOR. IMMERSION, DURATION, 10 s.							NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.				×	_
SOLDERABILITY			SOLDER	RED A	T SOL	DER T	MPERATU	JRE,		SOLDER SHALL COVER A MINIMUM OF 95					
		230±5 ℃ FOR INSERTION DURATION, 5 s.							% OF THE SURFACE BEING IMMERSED.				×		
REMARKS DRAWN								DESIGNED	CHECKED	APF	ROVED	RELE	ASED		
NOTE1:INCLUDING THE TEMPERATURE RISE BY CURRENT. NOTE2:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE PCB ON BOARD, AFTER PCB BOARD,OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERIM STORAGE DURING TRANSPORTATION. Unless otherwise specified, refer to JIS C 5402. O4.04.16								J. Qna 04.04.16	J.	ana 04.16					
Note QT:C								st							
HS.	HIR	OSEI	ELECTR)., LTI	_{D.} SF	ECIFIC	ATI	ON S	SHEET PART I	NO. 1 — * P —	2. 5	DSA	(05	5)
CODE NO.(O	LD)		[DRAWI			. 2 2 4 2	_		ART NO.	CI 5.4				1/